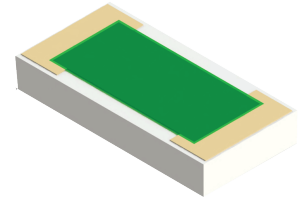


RM1005ZZ-XXXXWN-91 Features:

- Single-Sided Terminals w/ Backplane Configuration
- Solder, Epoxy or Wirebondable Terminals
- Solder or Epoxy Mount Backplane
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel and Waffle Pack Available (Standard is bulk)



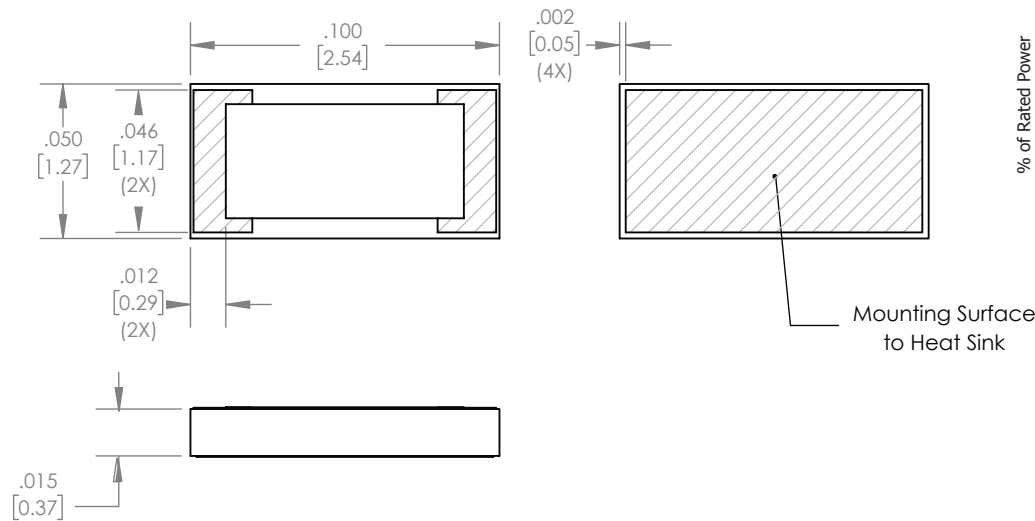
Actual Size

RM1005ZZ-XXXXWN-91 Parameters:

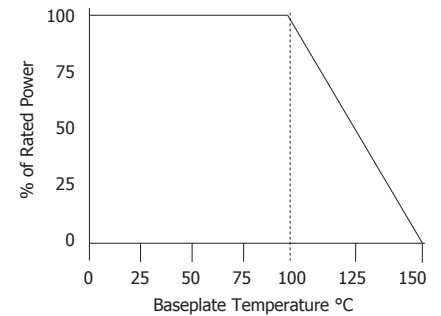
Resistance Range:	0.5Ω - 1MΩ
Rated Power:*	2.5W
Construction:	Thick Film on 0.015" Al ₂ O ₃
Operating Temperature:	-55 to +150°C

* Rating based on ≤100°C constant baseplate temperature

RM1005ZZ-XXXXWN-91 Dimensions:



RM1005ZZ-XXXXWN-91 Power Derating Curve



Dimensions in inches [mm]
Tolerance is ± 0.005 [0.13] unless otherwise stated

Ordering Information:

Example Part Number: RM1005CC-50R0GN-91

RM	1005	ZZ	-	XXXX	W	N	-	91	UU
Prefix for Resistor w/ Single-Sided Terminals and Backplane				Value Code	Tolerance	Normal Inspection Contact factory for additional options		Substrate	Packaging
Size	1005			50R0 - 50Ω 1000 - 100Ω 1001 - 1KΩ	1002 - 10KΩ 1003 - 100KΩ 1004 - 1MΩ	F - 1% G - 2% J - 5%		91 - 0.015" Al ₂ O ₃	Blank - Bulk WP - Waffle Pack TR - Tape & Reel

Terminal Metallization

AS -	Tin Lead over Platinum Palladium Gold
CB -	Tin Lead over Nickel over Silver
CC -	100% Matte Tin over Copper over Silver
CT -	100% Matte Tin over Nickel over Silver
EA -	Gold I/O Terminals w/ Palladium Silver Backplane
FA -	Gold I/O Terminals w/ Platinum Gold Backplane
GA -	Gold

RoHS	Magnetic	Solder	Epoxy	Wirebond
No	No	Yes	No	No
No	Yes	Yes	No	No
Yes	No	Yes	No	No
Yes	Yes	Yes	No	No
Yes	No	Yes (Backplane)	Yes	Yes (I/O Terminals)
Yes	No	Yes (Backplane)	Yes	Yes (I/O Terminals)
Yes	No	No	Yes	Yes

Barry Industries reserves the right to change part number and/or process without notification.

RM1005ZZ-XXXXWN-91 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65 to +125 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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